



# BAT46WJ-Q

Schottky barrier diode

23 August 2021

Product data sheet

## 1. General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a very small and flat lead SOD323F (SC-90) Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Low forward voltage
- Reverse voltage  $V_R \leq 100$  V
- Very small and flat lead SMD plastic package
- Low capacitance
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- High-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection



## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_R$	reverse voltage		-	-	100	V
$V_F$	forward voltage	$I_F = 250$ mA; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; pulsed; $T_{amb} = 25$ °C	-	710	850	mV
$I_R$	reverse current	$V_R = 75$ V; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; pulsed; $T_{amb} = 25$ °C	-	1	4	$\mu$ A

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SC-90 (SOD323F)	 aaa-003679
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT46WJ-Q	SC-90	plastic, surface-mounted package; 2 leads; 1.7 mm x 1.25 mm x 0.7 mm body	SOD323F

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BAT46WJ-Q	JK

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage			-	100	V
$I_F$	forward current			-	250	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p < 10$ ms; square wave; $T_{j(\text{init})} = 25$ °C		-	2.5	A
$P_{\text{tot}}$	total power dissipation	$T_{\text{amb}} \leq 25$ °C	[1] [2]	-	400	mW
			[3] [2]	-	715	mW
$T_j$	junction temperature			-	150	°C
$T_{\text{amb}}$	ambient temperature			-55	150	°C
$T_{\text{stg}}$	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	310	K/W
			[3] [2]	-	-	175	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	35	K/W

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

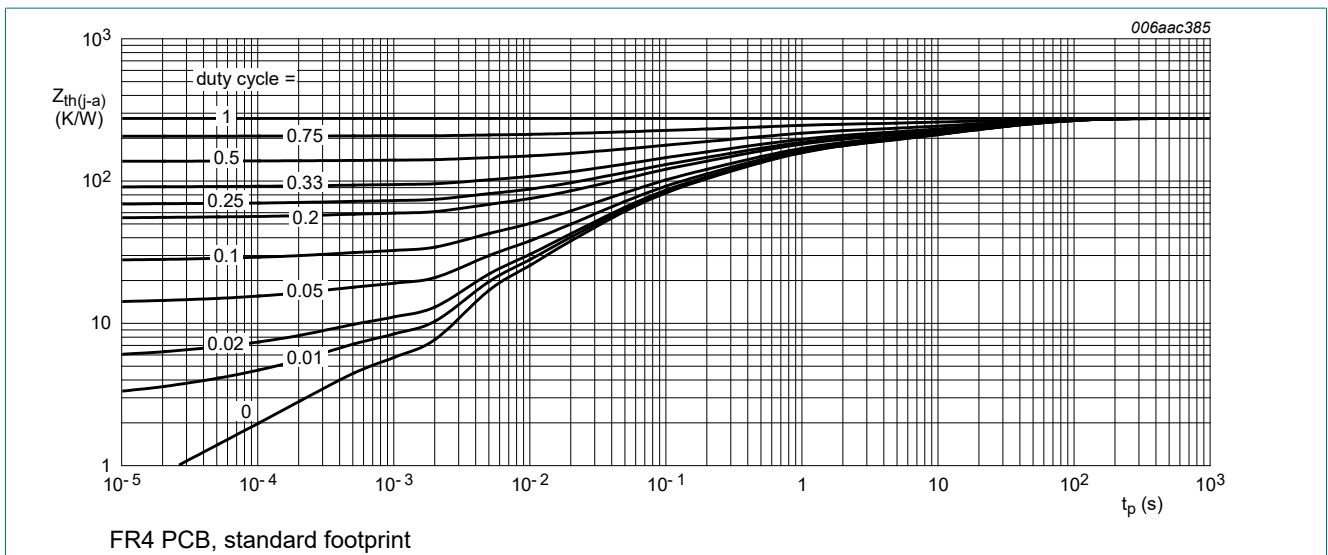


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

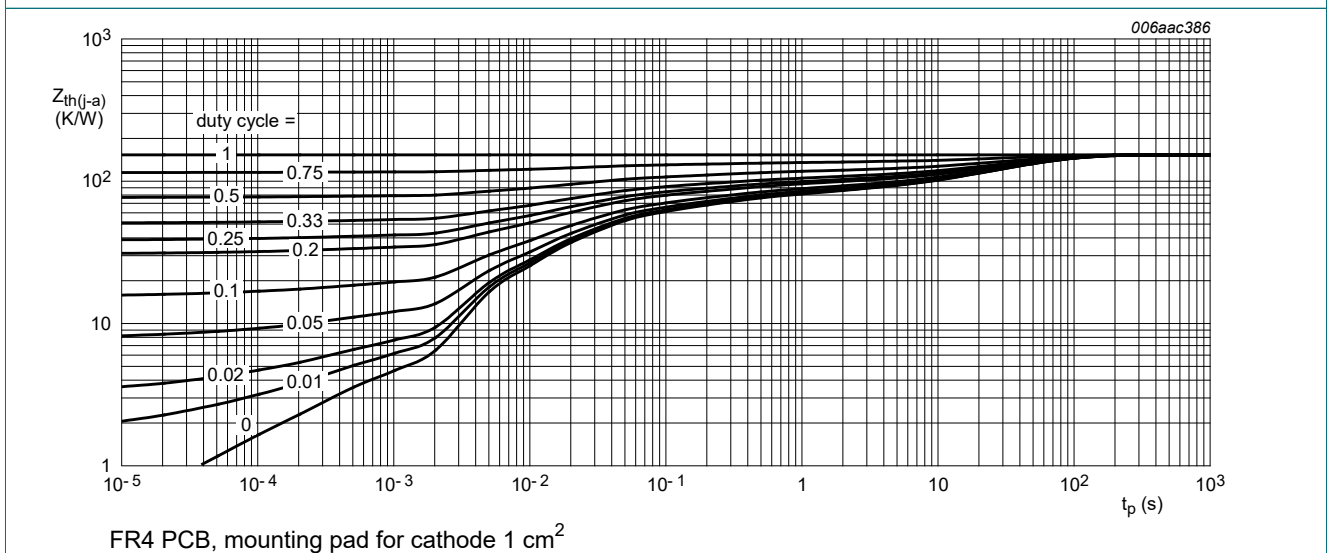
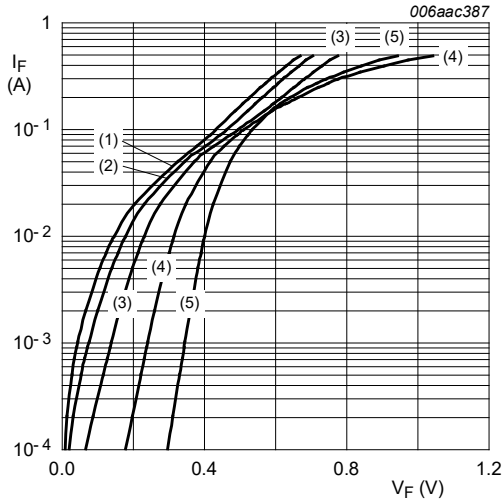


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

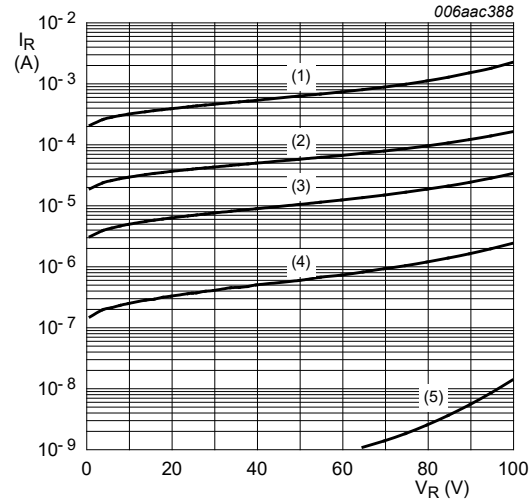
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	175	200	mV
		I <sub>F</sub> = 10 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	315	350	mV
		I <sub>F</sub> = 10 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = -40 °C	-	-	470	mV
		I <sub>F</sub> = 50 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	415	475	mV
		I <sub>F</sub> = 50 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = -40 °C	-	-	560	mV
		I <sub>F</sub> = 250 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	710	850	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1.5 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	0.2	0.5	μA
		V <sub>R</sub> = 1.5 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 60 °C	-	-	12	μA
		V <sub>R</sub> = 10 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	0.3	0.8	μA
		V <sub>R</sub> = 10 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 60 °C	-	-	20	μA
		V <sub>R</sub> = 50 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	0.7	2	μA
		V <sub>R</sub> = 50 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 60 °C	-	-	44	μA
		V <sub>R</sub> = 75 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	1	4	μA
		V <sub>R</sub> = 75 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 60 °C	-	-	80	μA
		V <sub>R</sub> = 100 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>amb</sub> = 25 °C	-	2	9	μA
		V <sub>R</sub> = 100 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 60 °C	-	-	120	μA
		V <sub>R</sub> = 100 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; pulsed; T <sub>j</sub> = 85 °C	-	-	600	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	39	pF
		V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	21	pF
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 10 mA; I <sub>R</sub> = 10 mA; I <sub>R(meas)</sub> = 1 mA; R <sub>L</sub> = 100 Ω; T <sub>amb</sub> = 25 °C	-	5.9	-	ns



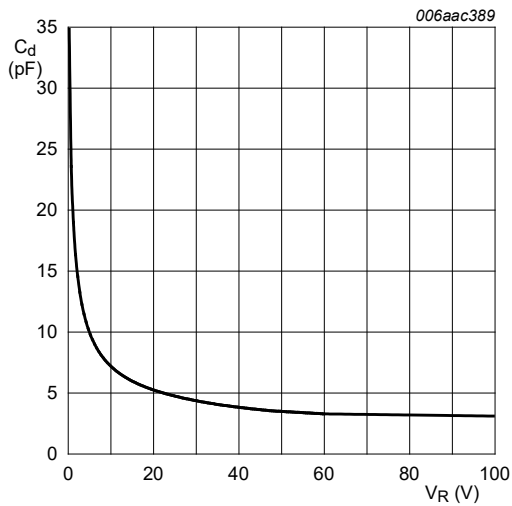
- (1)  $T_{amb} = 150^\circ\text{C}$
- (2)  $T_{amb} = 125^\circ\text{C}$
- (3)  $T_{amb} = 85^\circ\text{C}$
- (4)  $T_{amb} = 25^\circ\text{C}$
- (5)  $T_{amb} = -40^\circ\text{C}$

Fig. 3. Forward current as a function of forward voltage; typical values



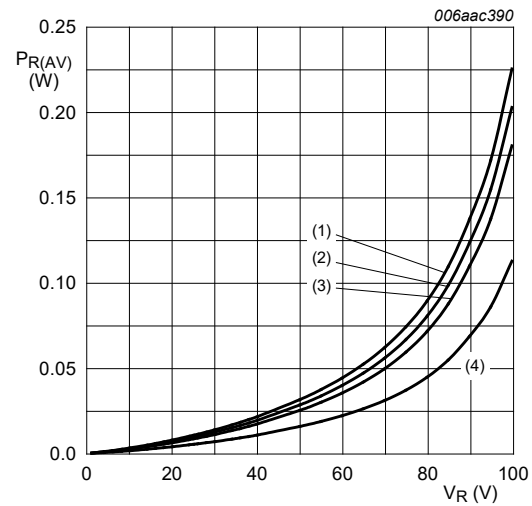
- (1)  $T_{amb} = 125^\circ\text{C}$
- (2)  $T_{amb} = 85^\circ\text{C}$
- (3)  $T_{amb} = 60^\circ\text{C}$
- (4)  $T_{amb} = 25^\circ\text{C}$
- (5)  $T_{amb} = -40^\circ\text{C}$

Fig. 4. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$ ;  $T_{amb} = 25^\circ\text{C}$

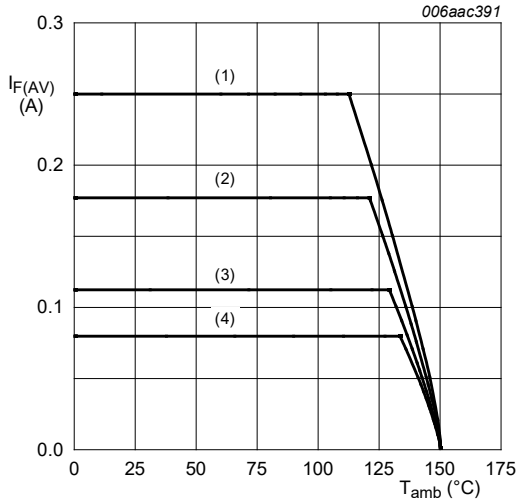
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 125^\circ\text{C}$

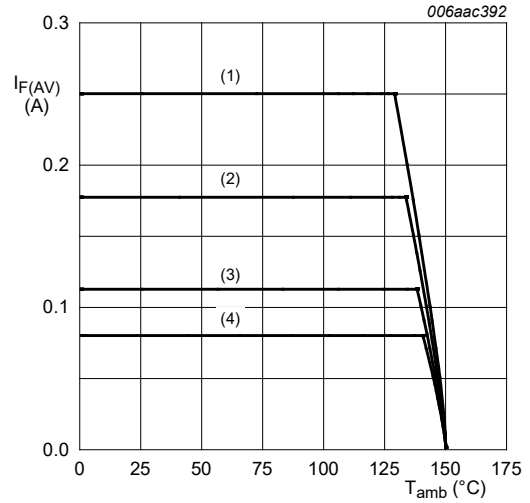
- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

Fig. 6. Average reverse power dissipation as a function of reverse voltage; typical values



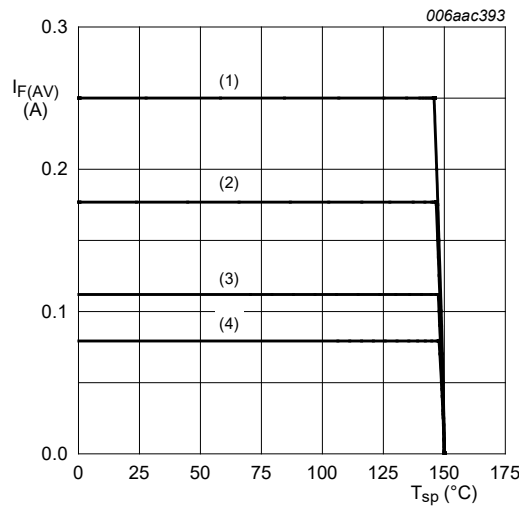
FR4 PCB, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 7.** Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

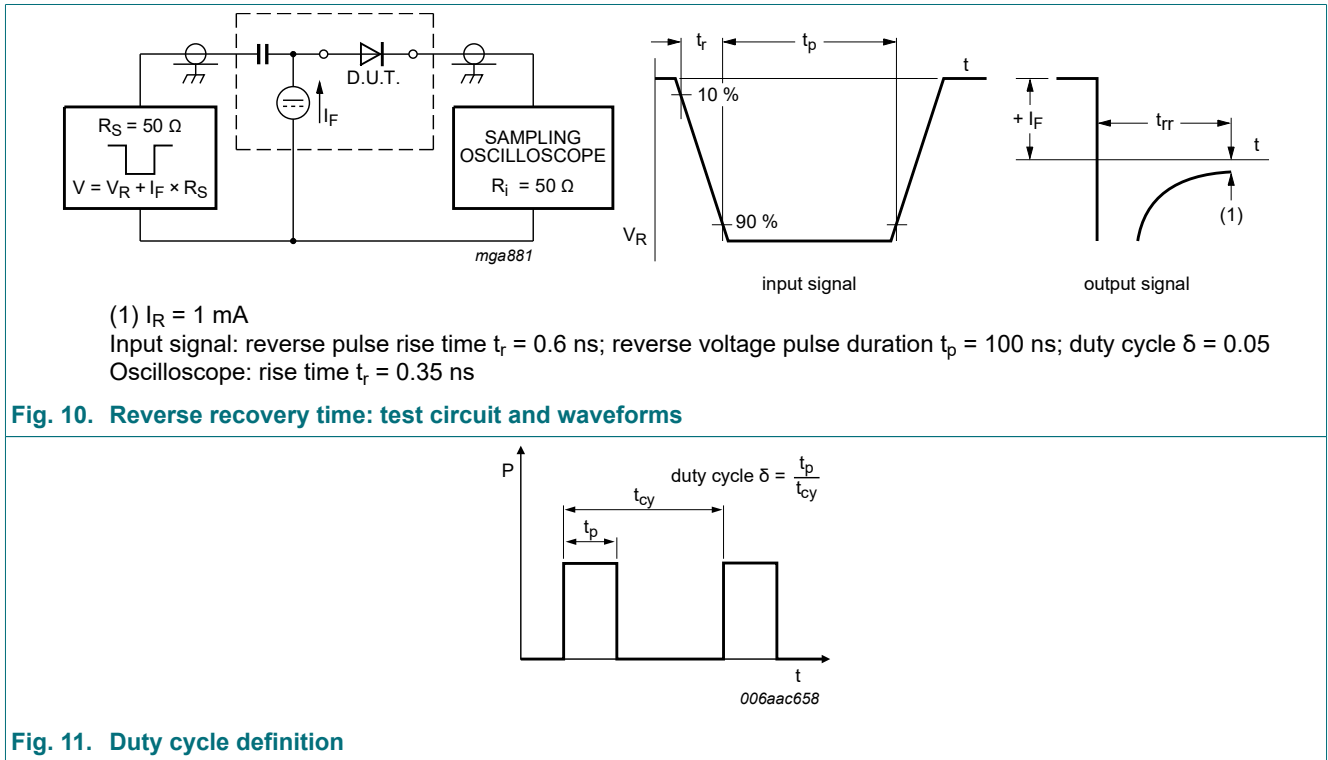
**Fig. 8.** Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 9.** Average forward current as a function of solder point temperature; typical values

### 11. Test information



The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.



## 12. Package outline

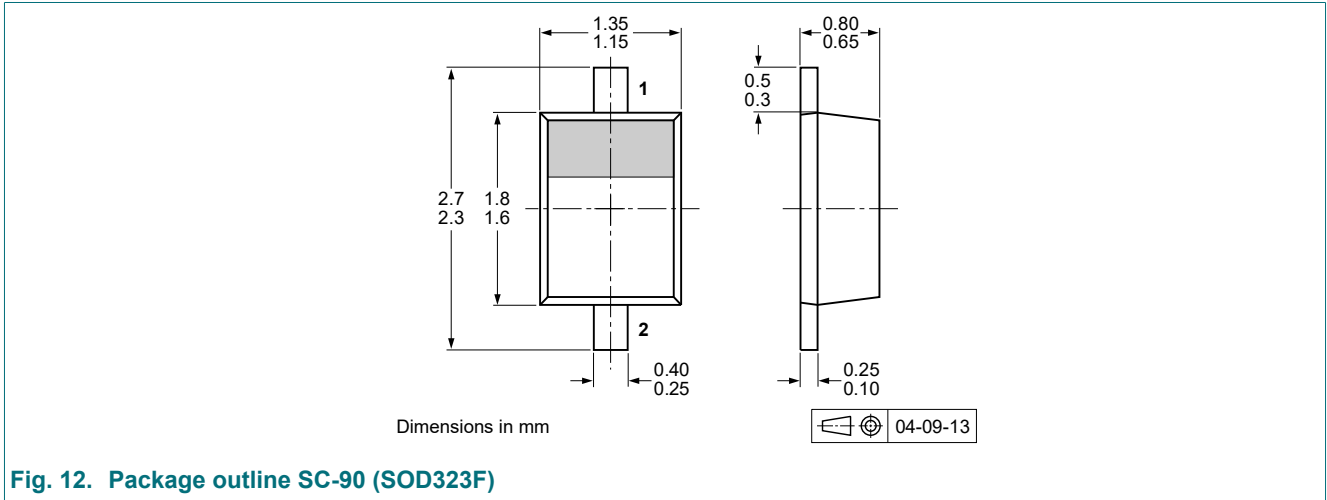


Fig. 12. Package outline SC-90 (SOD323F)

### 13. Soldering

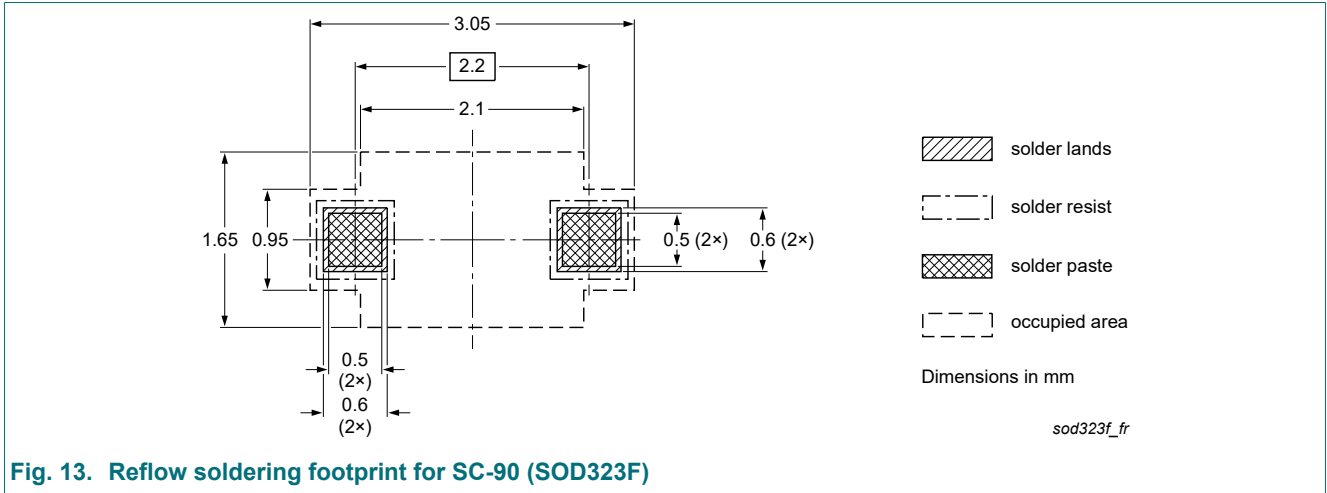


Fig. 13. Reflow soldering footprint for SC-90 (SOD323F)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BAT46WJ-Q v.1	20210823	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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